Thank you for attending the 2018 IEEE 68th Electronic Components and Technology Conference, sponsored by the IEEE Electronics Packaging Society (EPS), last week in San Diego!

I am pleased to let you know that this year's conference has been a resounding success and has set several new ECTC records! I would like to thank all authors, presenters, invited speakers, program committee members, exhibitors, sponsors, volunteers, and all attendees who contributed to such success!!

Here are some conference statistics that you may be interested to know:

- 1756 attendees, the highest attendance ever at an ECTC in its 68-year long history
- Attendees came from 28 different countries all around the world
- 369 technical papers, presented in 36 oral and five interactive presentation sessions, including a student interactive presentation session
- 18 professional development courses attended by 480 participants – another new record
- 36 corporate sponsors with a record level of industry support - more coming in at high value Gala Gold and Silver sponsorship levels, including a new Platinum sponsor
- 106 Technology Corner exhibit booths – all exhibitors this year have already committed to return next year!

In addition to the regular daytime sessions and courses, seven other well-attended special sessions and panel discussions were held on various days of the conference:

- ECTC Panel Session
  - Co-chaired by IEEE EPS President Avi Bar-Cohen of Raytheon and Chris Bailey of University of Greenwich on Heterogeneous Integrated System co-design
- ECTC Plenary Session
  - Chaired by Kemal Aygun of Intel Corporation on the impact of Artificial Intelligence on system design
- IEEE EPS Seminar
  - Co-chaired by Yasumitsu Orii of Nagase, Japan and Sheigenori Aoki of Fujitsu, Japan, on high-density packaging technologies
- Emerging Technologies Special Session
  - Co-chaired by W. Hong Yeo of Georgia Tech and C. S. Premachandran of GLOBALFOUNDRIES on soft material-enabled electronics for emerging applications
- ECTC Special Session
  - Chaired by Florian Herrault of HRL Laboratories on new assembly methods and applications
- ECTC/ITHERM Women's Panel
  - Co-chaired by Cristina Amon of University of Toronto and Tanja Braun of Fraunhofer IZM on enhancing women's participation in engineering
- ECTC/ITHERM Young Professionals Panel (new this year)
  - Chaired by Yan Liu of Medtronic, Inc. on career development for young professionals

The Heterogeneous Integration Roadmap Workshop, sponsored by the IEEE EPS, EDS and Photonics Societies together with SEMI and ASME EPPD, was also held at our conference for packed audience this year.

Finally, my special thanks to the ECTC Keynote Speaker, B.C. Ooi, Senior Vice President of Global Operations at Broadcom Inc., for his luncheon address on packaging advancement to enable game changing applications such as artificial intelligence, autonomous cars, and wearables. B.C. highlighted that the 2.5D integration will be the technology of choice for IDMs, and the global supply chain needs to focus on areas such as yield improvement, capacity/reliability of

supply, and the ways to handle cost of excursions/misprocessing. He issued a call to action to the industry on five key items to make 2.5D integration a mainstream packaging technology.

I would like to thank our corporate sponsors – particularly our Platinum Sponsor ASE Group; our Gala Gold sponsors Amkor, Atotech, Cadence, Deca Technologies, Dow Electronic Materials, IST Group, Lintec, Nepes, PacTech, SPTS, Unity and Evatech; our Gala Silver Sponsors Applied Materials, IBM, Micron, SPIL, Süss MicroTec, Lam Research, and Zeiss; and additional Special, Program, and Media sponsors.

Photos taken at the conference are now available on Flickr.

Next year's conference will be held 28 – 31 May 2019, at The Cosmopolitan of Las Vegas, Las Vegas, Nevada, USA.

Seeking your support to help build on the success of the 68th ECTC and make 2019 another great year for ECTC! I hope to see you in Las Vegas!!

Best Regards,

Sam Karikalan
General Chair, 2018 IEEE 68th Electronic Components and Technology Conference
Broadcom Inc.